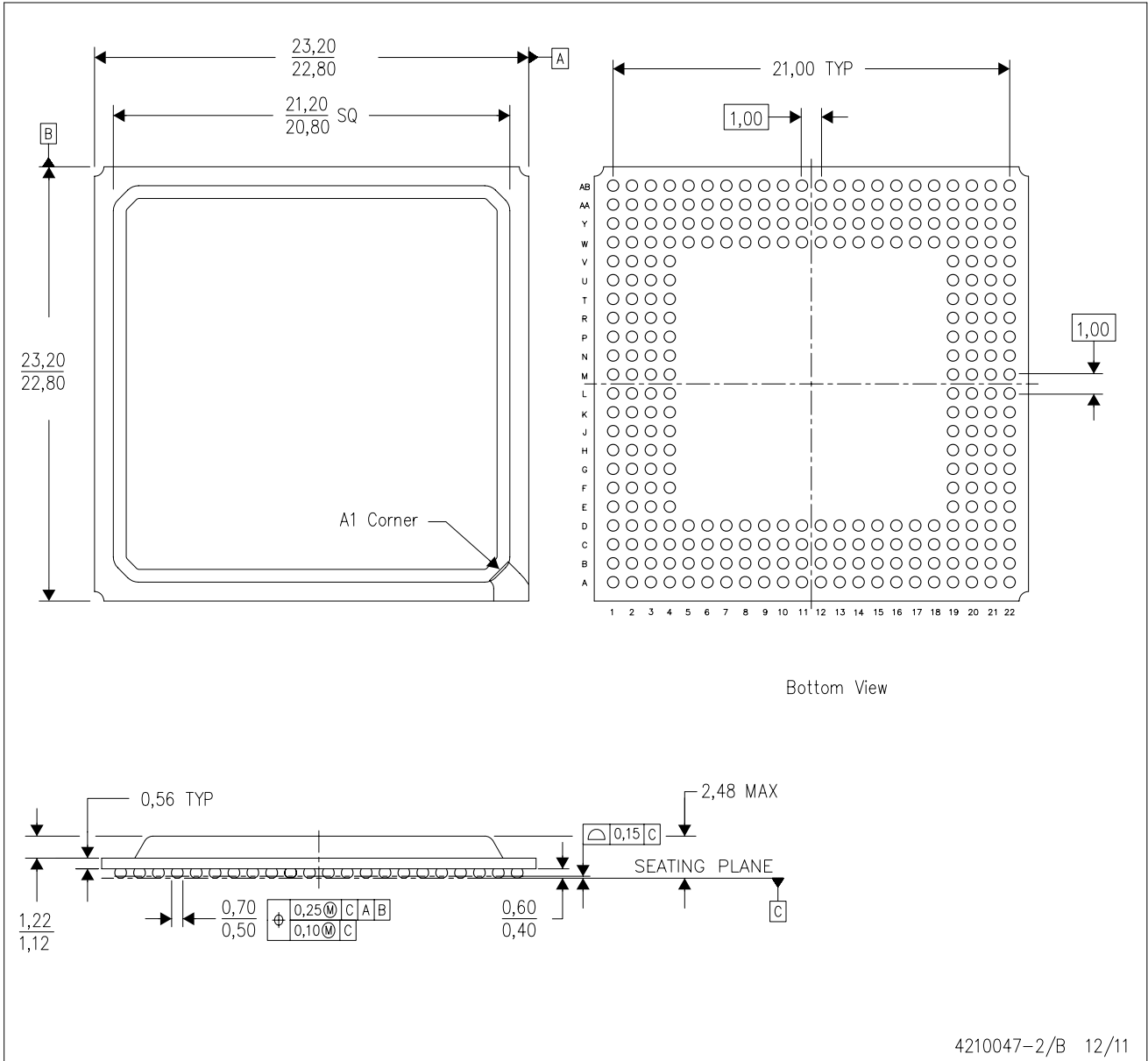


ZDB (S-PBGA-N288)

PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-151
- D. Thermally enhanced plastic package
- E. This package is a Pb free solder ball design.

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